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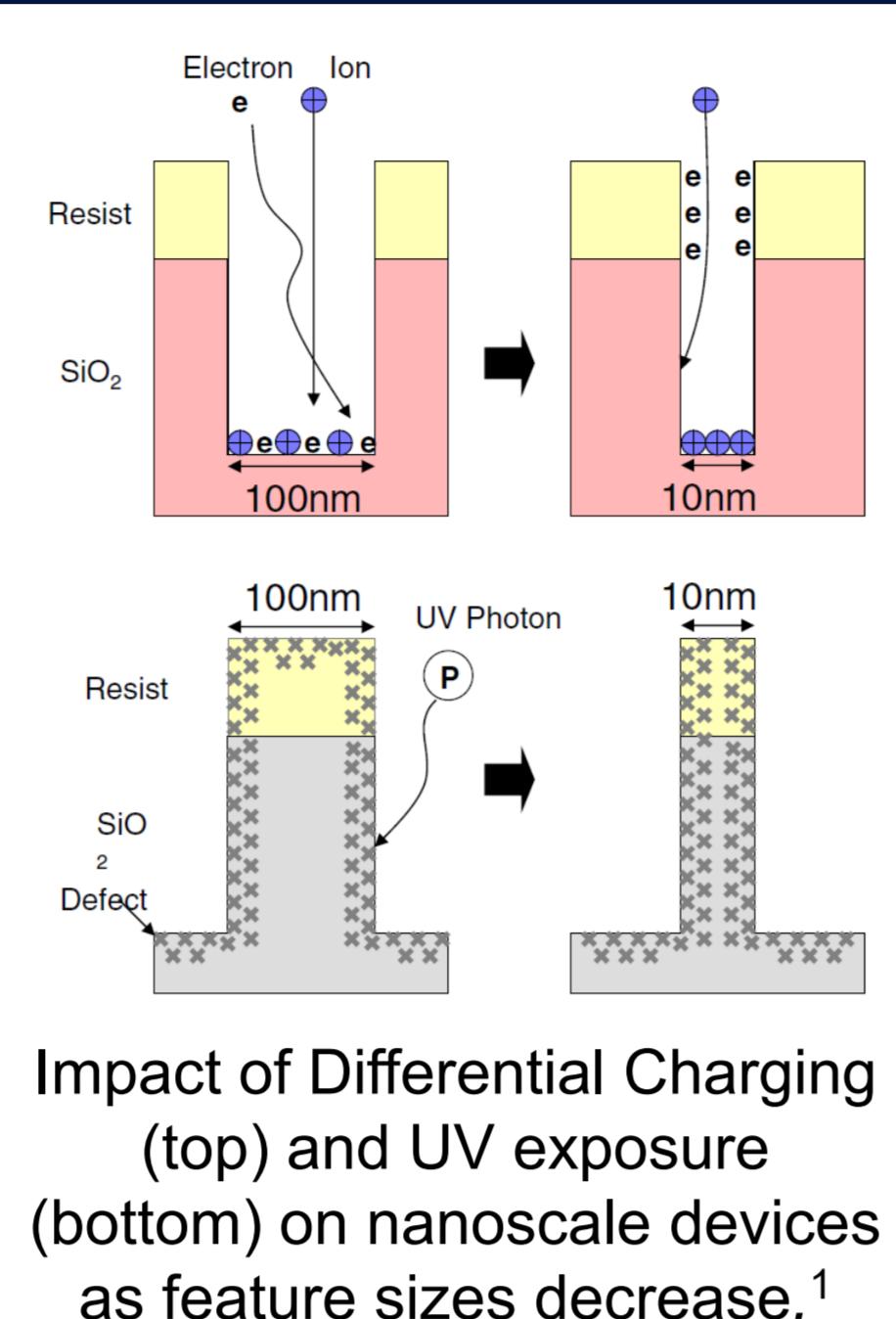
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Motivation

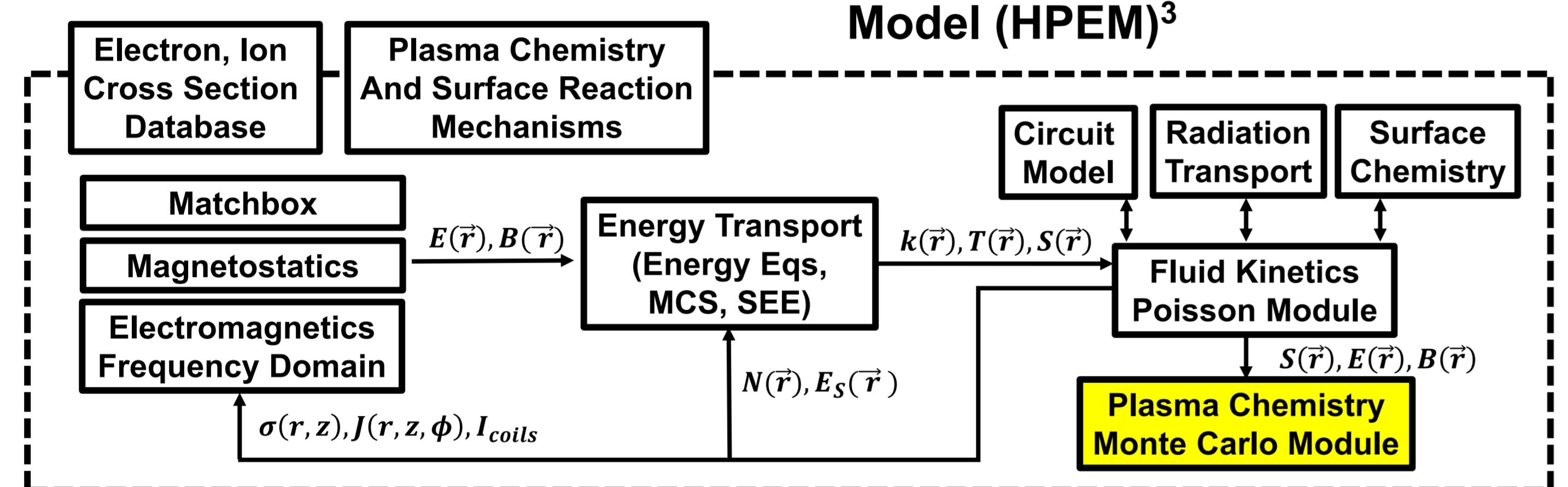
- Plasma etching and deposition are essential for microelectronics fabrication, requiring precise control of ion energy and angular distributions (EADs) hitting the wafer to enable critical surface reactions.
- However, plasma processes can negatively impact electrical and optical properties of nanodevices due to:
 - Differential charging of features - distorts ion trajectories leading to defects (e.g. bowing) or ARDE.
 - UV photons - can cause surface defects (dangling bonds).
- These effects should become more pronounced as device dimensions shrink, especially in 2-dimensional devices with near monolayer thickness.
- Energetic neutral beams offer a potential damage-free alternative for nanoscale fabrication².



How can we control and optimize the energy and angular distribution of neutrals hitting the wafer?

Modelling Tool

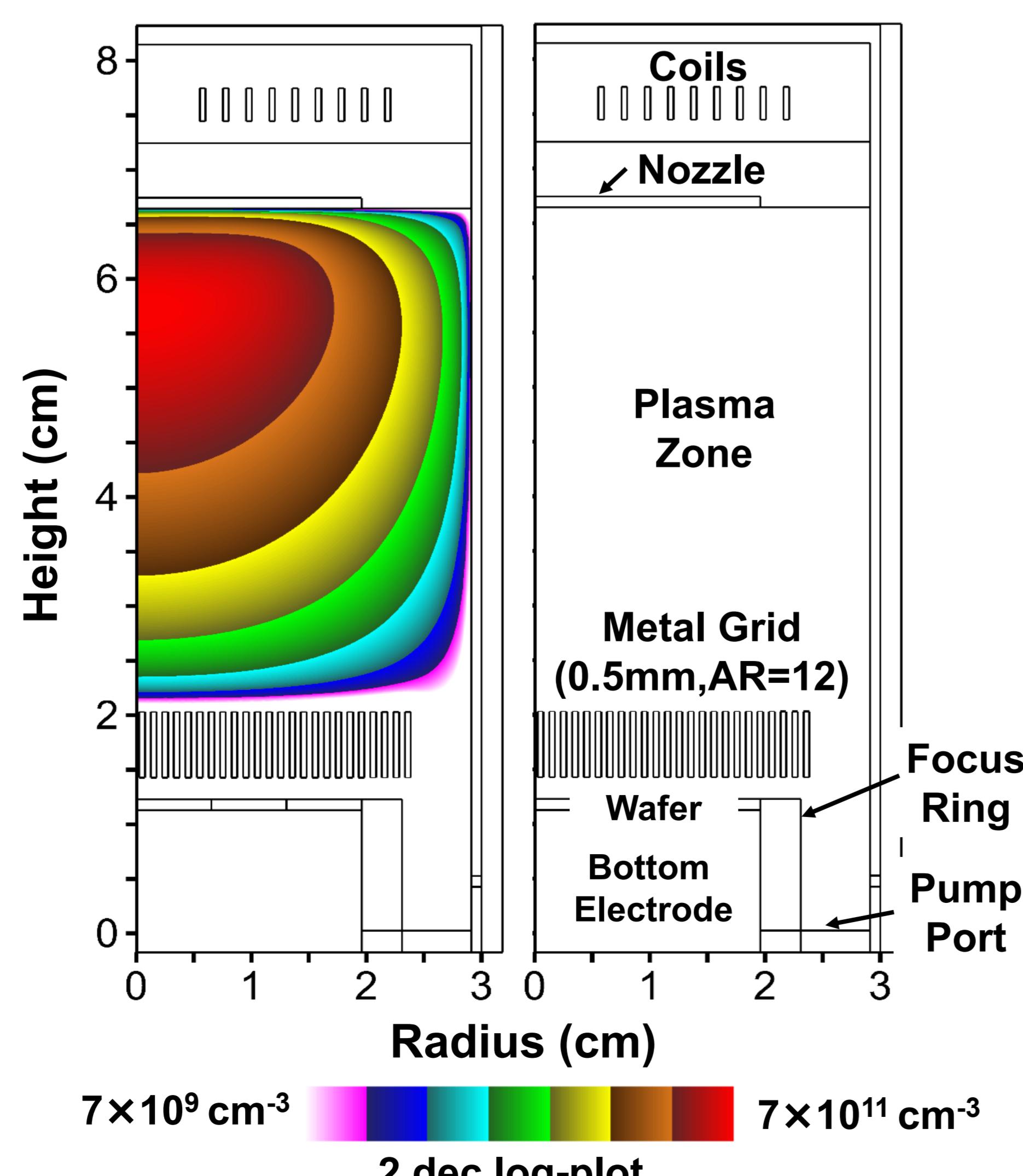
2D Hybrid Plasma Equipment Model (HPEM)³



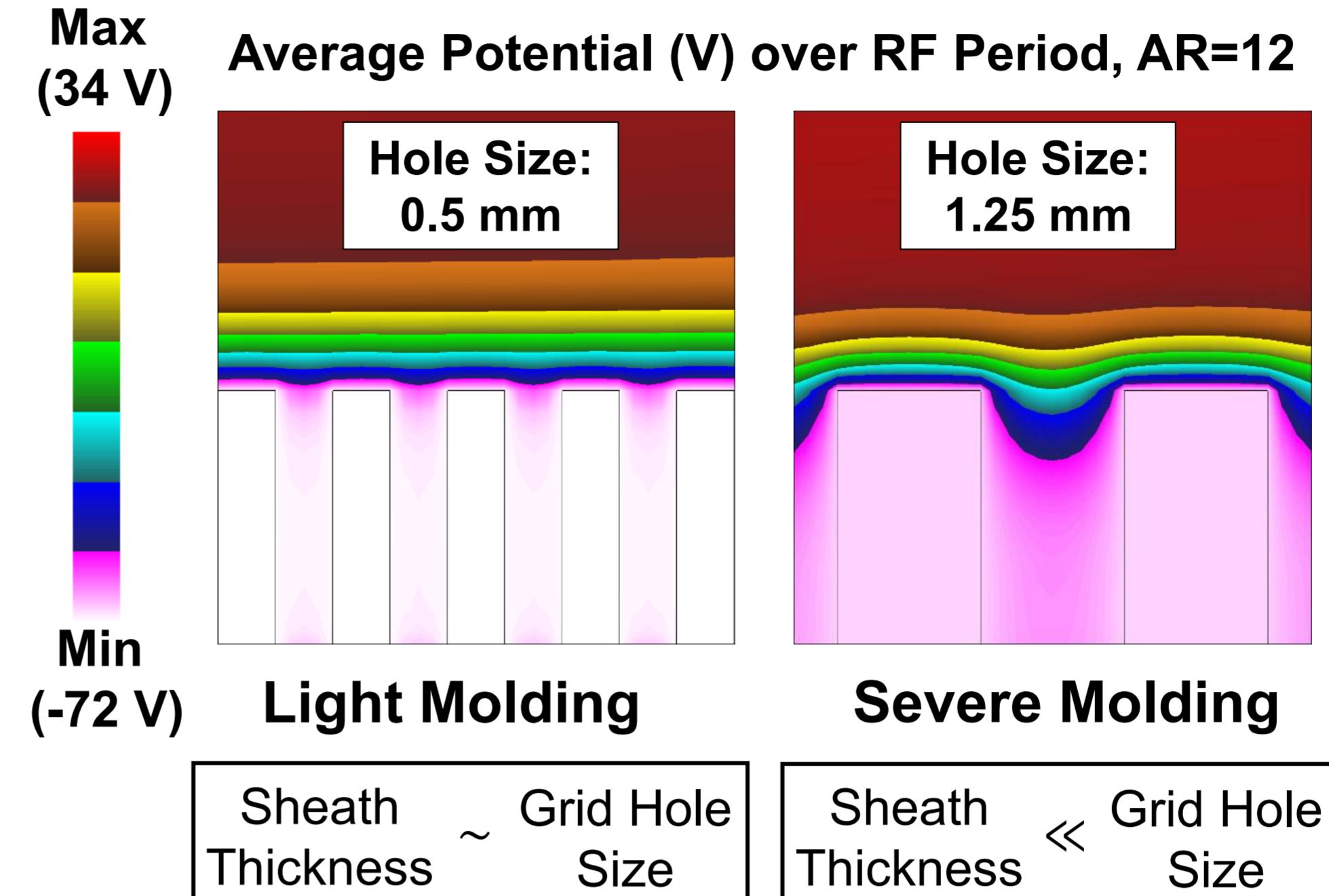
- HPEM is a simulation tool which combines kinetic and fluid methods to model the physical and chemical behavior of low-temperature plasmas.
- The Plasma Chemistry Monte Carlo (PCMC) module uses source terms and electric/magnetic fields from HPEM to launch and track ion and neutral particles until they hit a surface.

Neutral Beam Reactor Geometry

- Neutral beams can be generated by accelerating ions toward a biased grid, where they reflect and neutralize on the aperture walls.
- HPEM has been improved to model ion reflection from the grid, enabling the calculation of energy and angular distributions of the neutrals hitting the grid.
- Inductively Coupled Plasma (ICP) at 50 W.
- Argon at 20 mTorr and 400 K.
- Metal grid with RF bias: 100 V, 10 MHz.
- Bottom Electrode grounded.
- Variable Grid Hole Size (0.5-1.25 mm) and aspect ratio (6-24).
- Assumptions:
 - Charge-exchange reactions are not considered.
 - All argon ions reflect elastically and specularly from the grid as ground state neutrals.



Effect of Plasma Molding

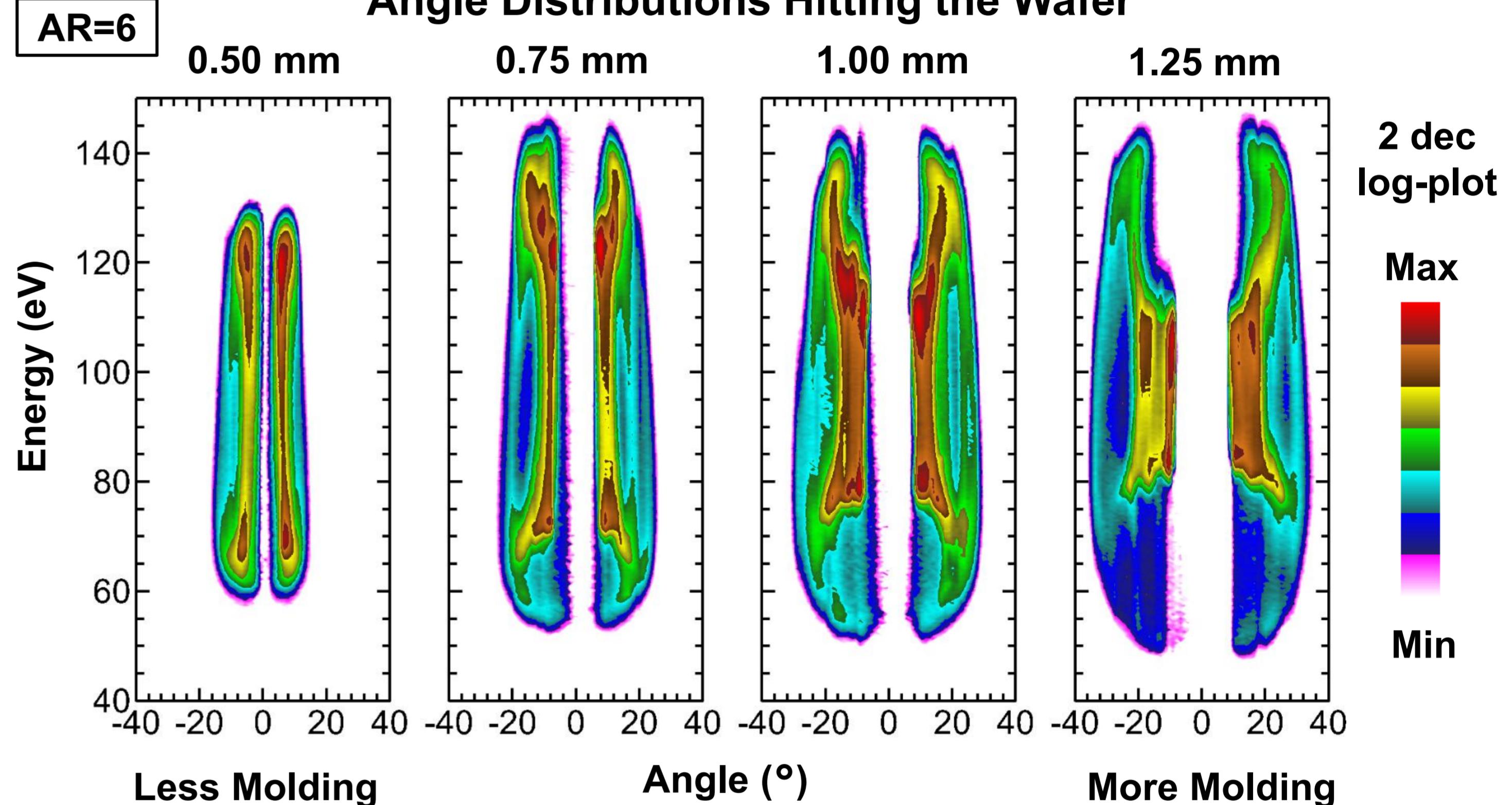


The degree of plasma molding over the grid holes influences the ion trajectories⁴.

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Severe plasma molding favors stronger ion deflection toward the grid.

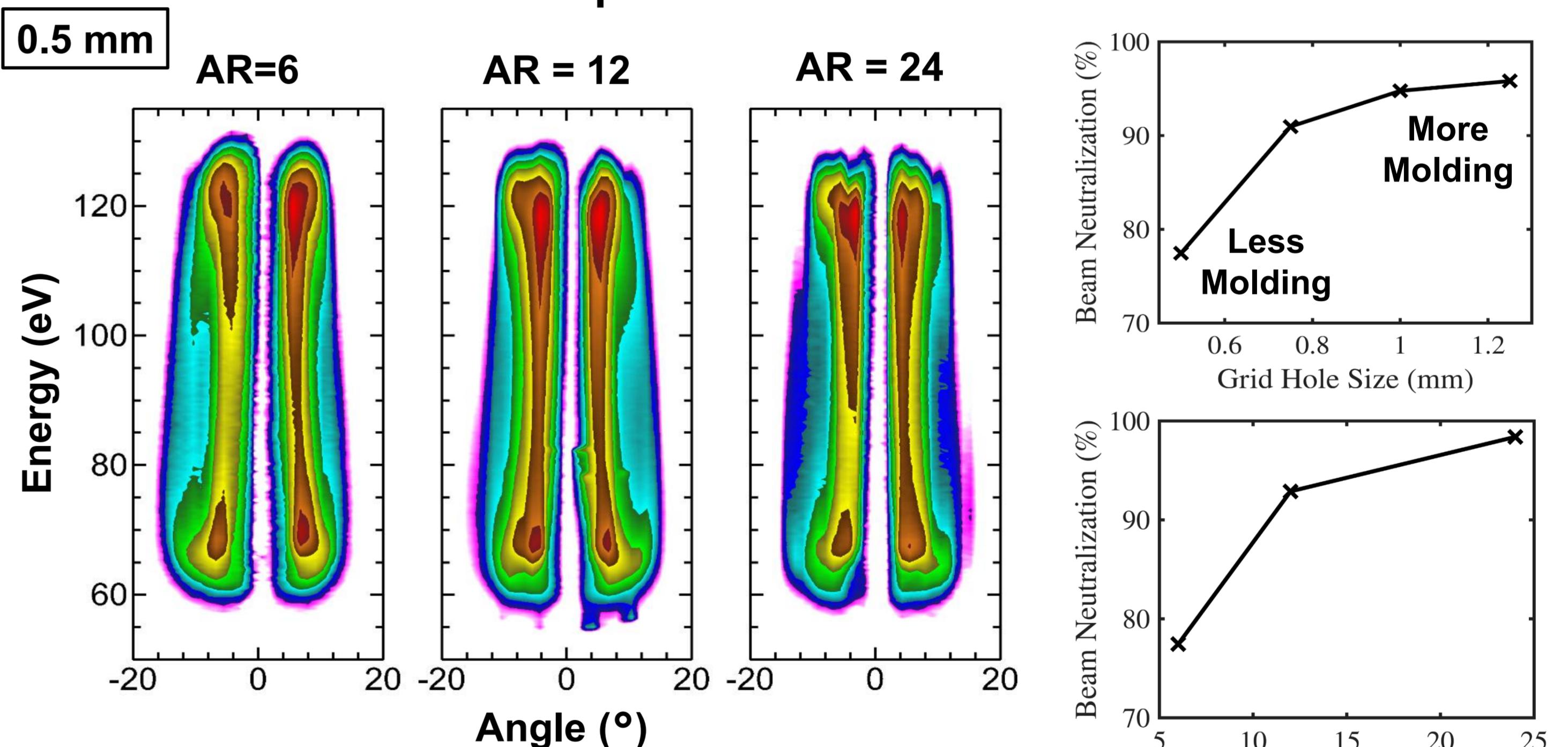
↓
Higher neutralization but reflected neutrals hit grid with larger angles.

Effect of Grid Hole Size on the Neutral Energy and Angle Distributions Hitting the Wafer



- Few neutrals at very small angles (ions must be deflected to collide with grid).
- Lighter molding leads to angularly-narrow distributions and severe molding to broader distributions with complex shapes (curved sheath).

Effect of Grid Aspect Ratio and Beam Neutralization



- Varying aspect ratio does not change the distribution function significantly (plasma molding is a local phenomenon).
- Beam neutralization is lower for lighter molding but can be increased independently by increasing the grid aspect ratio.

Summary

- In principle, neutral beams with tunable energy and angular distributions can be achieved while maintaining high particle fluxes ($\sim 10^{15} - 10^{16} \text{ cm}^{-2} \text{ s}^{-1}$).
- Plasma sheath molding plays a key role in defining the distribution functions and can be controlled by adjusting the grid aperture and/or plasma parameters.
- To achieve an optimal narrow-angle hot neutral distribution, the grid geometry and operating conditions should be tuned to obtain light sheath molding.
- Beam neutralization can be improved by increasing the grid aspect ratio.

References

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